

ABSTRACT OF THE DISCLOSURE

A polishing pad for polishing semiconductors and  
5 other planar substrates in the presence of a slurry  
comprising abrasive particles and a dispersive agent is  
disclosed. The polishing pad includes a soluble component  
within a polymer matrix component. The soluble component  
includes particles soluble in the slurry sufficiently to  
10 provide a void structure in the polishing surface of the  
pad. The void structure enhances the polishing rate and  
uniformity by increasing the mobility of the abrasive  
particles while reducing scratching of the polished  
surface. Additives that further enhance polishing and/or  
15 assist in the removal of residues generated during  
polishing, such as surfactants and removers, are  
optionally incorporated in the soluble particles or  
topographically coated on the soluble particles.

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